



(0.635 mm) .025" PITCH • QMSS/QFSS SERIES

NRZ
14
Gbps



QMSS
Board Mates:
QFSS

QFSS
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QMSS

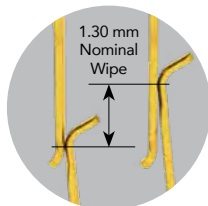
QMSS/QFSS
Standoffs:
SO

SPECIFICATIONS

Insulator Material:
Liquid Crystal Polymer
Terminal, Ground Plane & Shield Material:
Phosphor Bronze
Plating:
Au over 50 μ " (1.27 μ m) Ni
(Tin on Ground Plane Tail)
Operating Temp Range:
-55 °C to +125 °C
Voltage Rating:
300 VAC when mated

PROCESSING

Lead-Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max
(026-078)
Board Stacking:
For applications requiring more than two connectors contact ipg@samtec.com



QMSS	PINS PER ROW NO. OF PAIRS	06.75	PLATING OPTION	TYPE	A	OTHER OPTION
	-026, -052, -078 (52 total pins per bank / 40 signals + 12 grounds to shield = -D)		-L = 10 μ " (0.25 μ m) gold on contact, Matte Tin on tail	-D = Single- Ended		-K = (5.50 mm) .217" DIA Polyimide film Pick & Place Pad (N/A with - PC4)
	-016, -032, -048 (16 pairs per bank = -D-DP)			-D-DP = Differential Pair		-PC4 = 4 Power Pins/End (N/A with -A)

PACKAGING OPTION

Tape & Reel
Options (-TR &
-FR) available.
Visit series web
page and view
engineering prints
for complete
specifications.

View complete specifications at: samtec.com?QMSS

QFSS	PINS PER ROW NO. OF PAIRS	04.25	PLATING OPTION	TYPE	A	OTHER OPTION
	-026, -052, -078 (52 total pins per bank / 40 signals + 12 grounds to shield = -D)		-L = 10 μ " (0.25 μ m) gold on contact, Matte Tin on tail	-D = Single- Ended		-PC4 = 4 Power Pins/End (N/A with -A)
	-016, -032, -048 (16 pairs per bank = -D-DP)			-D-DP = Differential Pair		

PACKAGING OPTION

Tape & Reel
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Note:
Some lengths, styles and
options are non-standard,
non-returnable.

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